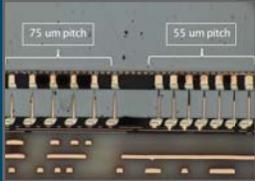


# Advanced Packaging Update: Market and Technology Trends

Vol. 3-1021



This issue of the Advanced Packaging Update features a financial analysis of OSATs, including performance metrics. Continuing semiconductor shortages and supply chain disruptions are discussed, including an update on automotive electronics. The special section on packaging trends for advanced semiconductor nodes includes a package forecast for silicon interposers and high-density fan-out. Packaging challenges for chipllets and especially 3D are discussed. Trends in high bandwidth memory (HBM) are discussed and a market forecast is provided.

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